TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π -MOS V)

SK2996

HIGH SPEED, HIGH VOLTAGE SWITCHING APPLICATIONS CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS**

Low Drain-Source ON Resistance : $R_{DS(ON)} = 0.74 \Omega \text{ (Typ.)}$

High Forward Transfer Admittance : $|Y_{fs}| = 6.8 \,\mathrm{S}$ (Typ.)

Low Leakage Current : $I_{DSS} = 100 \,\mu\text{A}$ (Max.) ($V_{DS} = 600 \,\text{V}$)

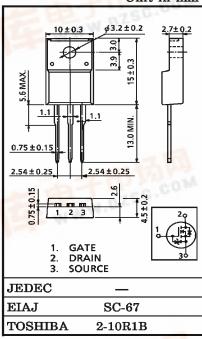
: $V_{th} = 2.0 \sim 4.0 \text{ V}$ Enhancement-Mode

 $(V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA})$

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERIST	SYMBOL	RATING	UNIT		
Drain-Source Voltage	$v_{ m DSS}$	600	V		
Drain-Gate Voltage (RGS	$v_{ m DGR}$	600	V		
Gate-Source Voltage	VGSS	±30	V		
Drain Current	DC	$I_{\mathbf{D}}$	10	A	
	Pulse	I_{DP}	30		
Drain Power Dissipation	$P_{\mathbf{D}}$	45	W		
Single Pulse Avalanche I	EAS	252	mJ		
Avalanche Current	I_{AR}	10	Α		
Repetitive Avalanche Ene	$\mathbf{E}_{\mathbf{A}\mathbf{R}}$	4.5	mJ		
Channel Temperature	$\mathrm{T_{ch}}$	150	°C		
Storage Temperature Ran	$\mathbf{T_{stg}}$	-55~150	°C		

INDUSTRIAL APPLICATIONS Unit in mm



Weight: 1.9 g

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	Rth (ch-c)	2.78	°C/W
Thermal Resistance, Channel to Ambient	R _{th (ch-a)}	62.5	°C/W

Note;

- * Repetitive rating; Pulse Width Limited by Max. junction temperature.
- ** V_{DD} = 90 V, Starting T_{ch} = 25°C, L = 4.41 mH, R_{G} = 25 Ω , I_{AR} = 10 A

This transistor is an electrostatic sensitive device. Please handle with caution.

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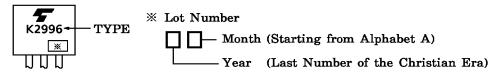
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

СПАВА	ĊΨΕ·DTQΨΤ¢	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
CHARACTERISTIC		SIMBOL	TEST CONDITION	MITIM.	IIF.		UNII
Gate Leakage Current		IGSS	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$		_	±10	μ A
Gate-Source Breakdown Voltage		V (BR) GSS	$I_{ extbf{G}}=\pm 10~\mu ext{A},~ ext{V}_{ extbf{DS}}=0~ ext{V}$	±30	_	_	v
Drain Cut-off	f Current	$I_{ m DSS}$	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	100	μ A
Drain-Source Voltage		V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	600	_	_	v
Gate Thresho	old Voltage	$v_{ m th}$	$V_{\mathrm{DS}} = 10 \mathrm{V}, \mathrm{I_D} = 1 \mathrm{mA}$	2.0	_	4.0	V
Drain-Source	ON Resistance	RDS (ON)	$V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$	_	0.74	1.0	Ω
Forward Train Admittance	nsfer	Y _{fs}	$V_{DS} = 10 \text{ V}, I_{D} = 5 \text{ A}$	3.4	6.8	_	s
Input Capaci	Input Capacitance			_	1500	_	
Reverse Transfer Capacitance		C _{iss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, $ f = 1 MHz	_	13	_	pF
Output Capa	Output Capacitance			_	140	_	
Switching Time	Rise Time	t _r	$V_{GS} \stackrel{10 \text{ V}}{\circ} V \stackrel{\text{I}_{D} = 5 \text{ A}}{\circ} V_{OUT}$ $R_{L} = 60 \Omega$ $V_{DD} = 300 \text{ V}$	_	15	_	
	Turn-on Time	ton		_	55	_	ns
	Fall Time	tf		-	27	_	ns
	Turn-off Time	t _{off}	$V_{ ext{IN}}: ext{t}_{ ext{r}}, ext{tf} < 5 ext{ ns}, \ ext{Duty} \leq 1\%, ext{t}_{ ext{W}} = 10 ext{} \mu ext{s}$	_	145	_	
Total Gate Charge (Gate- Source Plus Gate-Drain)		$\mathbf{Q}_{\mathbf{g}}$	$V_{DD} = 400 \text{ V}, V_{GS} = 10 \text{ V},$	_	38	_	nC
Gate-Source	Gate-Source Charge		$I_D = 10 A$	_	21] "C
Gate-Drain ("Miller") Charge		$Q_{ m gd}$			17	_	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	10	A
Pulse Drain Reverse Current	$I_{ m DRP}$	_	_	_	30	Α
Diode Forward Voltage	$v_{ m DSF}$	$I_{DR} = 10 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse Recovery Time	t _{rr}	$I_{ m DR} = 10 m A, V_{ m GS} = 0 m V$ $dI_{ m DR} / dt = 100 m A / \mu s$	_	1600	_	ns
Reverse Recovery Charge	Q_{rr}	$dI_{DR}/dt = 100 A/\mu s$		17	_	μ C

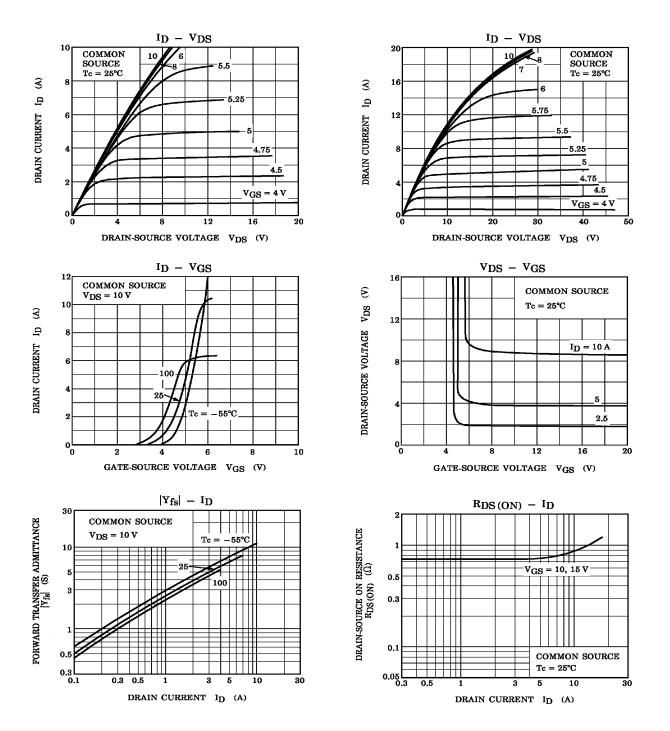
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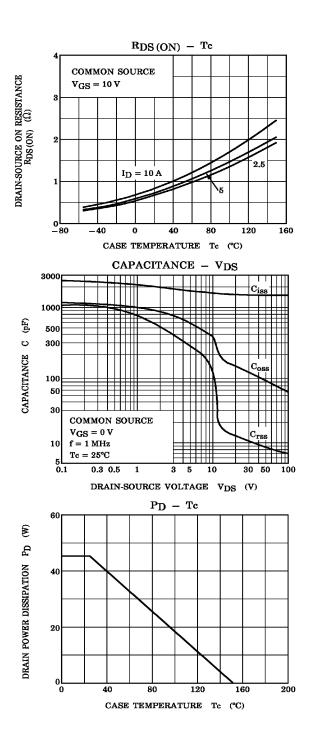
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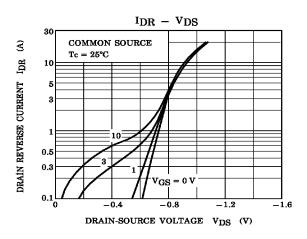


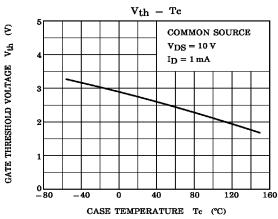
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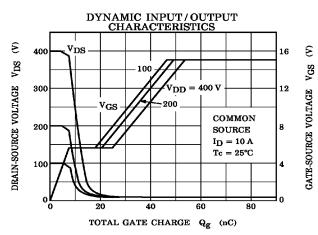


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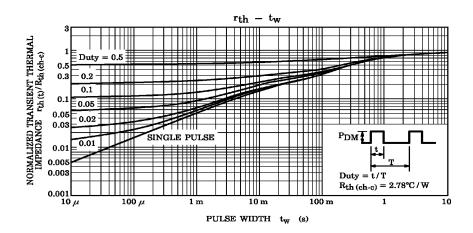


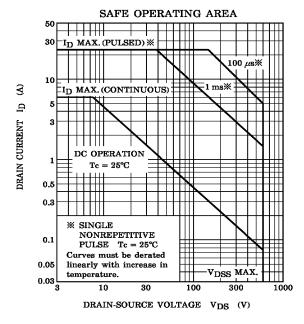


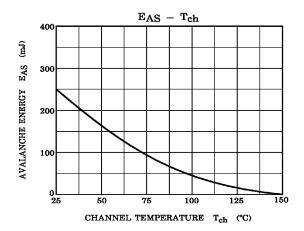


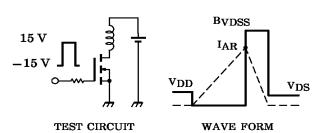


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Peak I_{AR} = 10 A, R_G = 25
$$\Omega$$
 $E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot (\frac{BVDSS}{BVDSS - VDD})$